



<b>Title of Change:</b>	Addition of ON Semiconductor Gresham, Oregon, as wafer fab location (I3T50 technology), currently manufactured in Fab2, Oudenaarde, Belgium for the <b>NCV7718DPR2G</b> product. New OPN will be dual source wafer fab.	
<b>Proposed Changed Material First Ship Date:</b>	30 October 2018	
<b>Current Material Last Order Date:</b>	N/A	
<b>Current Material Last Delivery Date:</b>	N/A	
<b>Product Category:</b>	Active components – Integrated circuits	
<b>Contact information</b>	Contact your local ON Semiconductor Sales Office	
<b>Samples</b>	Contact your local ON Semiconductor Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification.	
<b>Sample Availability Date:</b>	30 October 2017	
<b>PPAP Availability Date:</b>	30 October 2017	
<b>Additional Reliability Data</b>	Contact your local ON Semiconductor Sales Office or <Catherine.DeKeukeleire@onsemi.com>	
<b>Type of Notification</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.	
<b>Change Category:</b>	<b>Type of Change</b>	
Process – Wafer Production	New wafer diameter	
Process – Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor	
Design	Design Change in Active Elements	
Process – Assembly	Change of wire size	
<b>Description and Purpose:</b>		
Addition of ON Semiconductor Gresham, Oregon as wafer fab location (I3T technology, 200 mm fab), currently manufactured in Fab2, Oudenaarde, Belgium (150 mm fab) for the NCV7718DPR2G product. This will increase ON Semiconductor's wafer fab capacity and flexibility for this device.		
Minor design changes to improve performance and manufacturability.		
	<b>Before Change Description</b>	<b>After Change Description</b>
<b>Wafer Diameter</b>	150mm	200mm
<b>Wire Size</b>	1.0 mil	1.3 mil
<b>Reason / Motivation for Change:</b>	<b>Benefit of the change:</b> Provide additional wafer fab capacity and flexibility for manufacturing. <b>Risk for Late Release:</b> Possible supply disruptions.	
<b>Anticipated impact on fit, form, function, reliability, product safety or manufacturability</b>	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded.  No anticipated impacts.	





**Electrical Characteristic Summary:**

Electrical characteristics are not impacted.

**NOTE: CPK Report is attached.**

*To access file attachments on pdf copy of PCN, please be guided by the steps below:*

- 1. Download pdf copy of the PCN to your computer*
- 2. Open the downloaded pdf copy of the PCN*
- 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field*
- 4. Then click on the attached file/s*

**List of Affected Standard Parts:**

Current Part Number	Dual Source Part Number	Qualification Vehicle
NCV7718DPR2G	NCV7718CDPR2G	NCV7718CDPR2G